

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Kuei Shun Chen</td> <td>06/04/2010</td> </tr> <tr> <td>Meng-Wei Chen</td> <td>06/04/2010</td> </tr> <tr> <td>George Liu</td> <td>06/04/2010</td> </tr> <tr> <td>Jiann Yuan Huang</td> <td>06/04/2010</td> </tr> <tr> <td>Chia-Ching Lin</td> <td>06/04/2010</td> </tr> </tbody> </table>		Name	Execution Date	Kuei Shun Chen	06/04/2010	Meng-Wei Chen	06/04/2010	George Liu	06/04/2010	Jiann Yuan Huang	06/04/2010	Chia-Ching Lin	06/04/2010
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Jiann Yuan Huang	06/04/2010												
Chia-Ching Lin	06/04/2010												
RECEIVING PARTY DATA													
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.												
Street Address:	No. 8, Li-Hsin Road 6												
City:	Hsin-Chu												
State/Country:	TAIWAN												
Postal Code:	300-77												
PROPERTY NUMBERS Total: 1													
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>12835415</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	12835415								
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CORRESPONDENCE DATA													
Fax Number:	(214)200-0853												
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>													
Phone:	214-651-5000												
Email:	ipdocketing@haynesboone.com												
Correspondent Name:	HAYNES AND BOONE, LLP												
Address Line 1:	2323 Victory Avenue												
Address Line 2:	Suite 700												
Address Line 4:	Dallas, TEXAS 75219												
ATTORNEY DOCKET NUMBER:	24061.1474												
NAME OF SUBMITTER:	Rachel L.I. Davis												

OP \$40.00 12835415

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**PATENT
 REEL: 024675 FRAME: 0437**

Total Attachments: 3

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ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|------------------|----|---|
| (1) | Kuei Shun Chen | of | 5F, 22 634 Lane, Nan-Da Road
Hsin-Chu 300, Taiwan, R.O.C. |
| (2) | Meng-Wei Chen | of | 9F-1, No. 198-2, Sec. 3, Huilai Road, Xitun District
Taichung City 407, Taiwan, R.O.C. |
| (3) | George Liu | of | 4F, No. 70, Ren-ai Street
Shin-Chu City, Taiwan, R.O.C. |
| (4) | Jiann Yuan Huang | of | No. 2, Lane 9, Bade Road
Hsinchu City 300, Taiwan, R.O.C. |
| (5) | Chia-Ching Lin | of | No. 8, Lane 31, Chang-Ping Road, Sec. 2
Taichung City, Taiwan, R.O.C. |

have invented certain improvements in

**SYSTEM AND METHOD FOR PROVIDING ALIGNMENT
MARK FOR HIGH-K METAL GATE PROCESS**

for which we have executed an application for Letters Patent of the United States of America,

 X of even date filed herewith; and
 filed on July 13, 2010 and assigned application number 12/835,415; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said

invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.


AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Kuei Shun Chen

Residence Address: 5F, 22 634 Lane, Nan-Da Road
Hsin-Chu 300, Taiwan, R.O.C.

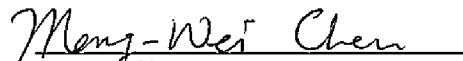
Dated: 2010. 06. 04


Inventor Signature

Inventor Name: Meng-Wei Chen

Residence Address: 9F-1, No. 198-2, Sec. 3, Huilai Road, Xitun District
Taichung City 407, Taiwan, R.O.C.

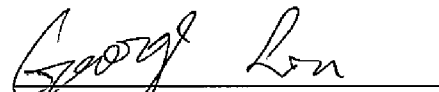
Dated: 2010. 06. 04


Inventor Signature

Inventor Name: George Liu

Residence Address: 7F, No. 288, Wenping Road
Shin-Chu City, Taiwan, R.O.C.

Dated: 2010. 06. 04


Inventor Signature

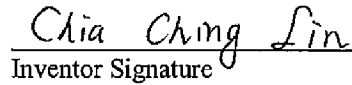
Inventor Name: Jiann Yuan Huang
Residence Address: No. 2, Lane 9, Bade Road
Hsinchu City 300, Taiwan, R.O.C.

Dated: 2010. 6. 4


Inventor Signature

Inventor Name: Chia-Ching Lin
Residence Address: No. 8, Lane 31, Chang-Ping Road, Sec. 2
Taichung City, Taiwan, R.O.C.

Dated: 2010. 6. 4


Inventor Signature